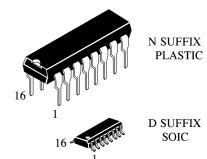
DUAL J-K FLIP-FLOP WITH SET AND RESET High-Speed Silicon-Gate CMOS

The IN74ACT109 is identical in pinout to the LS/ALS109, HC/HCT109. The IN74ACT109 may be used as a level converter for interfacing TTL or NMOS outputs to High Speed CMOS inputs.

This device consists of two J-K flip-flops with individual set, reset, and clock inputs. Changes at the inputs are reflected at the outputs with the next low-to-high transition of the clock. Both Q to Q outputs are available from each flip-flop.

- TTL/NMOS Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: 1.0 μA; 0.1 μA @ 25°C
- Outputs Source/Sink 24 mA



ORDERING INFORMATION

IN74ACT109N Plastic IN74ACT109D SOIC $T_A = -40^\circ$ to 85° C for all

packages

PIN ASSIGNMENT

1•	16] v _{CC}
2	15	RESET 2
3	14] J2
4	13] <u>K2</u>
5	12	CLOCK 2
6	11] SET 2
7	10] Q2
8	9] 22
	2 3 4 5 6 7	2 15 3 14 4 13 5 12 6 11 7 10

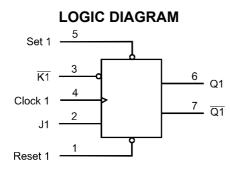
FUNCTION TABLE

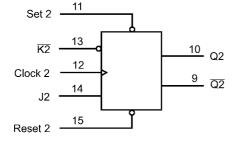
Inputs				Ou	tputs	
Set	Reset	Clock	J	ĸ	Q	Q
L	Н	Х	Х	Х	Н	L
Н	L	Х	Х	Х	L	Н
L	L	Х	Х	Х	H	H
Н	Н		L	L	L	Н
Н	Н	ן	Η	L	Toggle	
Н	Н	Ļ	L	Η	No Change	
Н	Н		Η	Н	Н	L
Н	Н	L	Х	Х	No Change	

X = Don't care

^{*}Both outputs will remain high as long as Set and Reset are low, but the output states are unpredictable if Set and Reset go high simultaneously.









MAXIMUM RATINGS^{*}

Parameter	Value	Unit
DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
DC Input Current, per Pin	±20	mA
DC Output Sink/Source Current, per Pin	±50	mA
DC Supply Current, V _{CC} and GND Pins	±50	mA
Power Dissipation in Still Air, Plastic DIP+	750	mW
SOIC Package+	500	
Storage Temperature	-65 to +150	°C
Lead Temperature, 1 mm from Case for 10	260	°C
Seconds		
(Plastic DIP or SOIC Package)		
	Parameter DC Supply Voltage (Referenced to GND) DC Input Voltage (Referenced to GND) DC Output Voltage (Referenced to GND) DC Input Current, per Pin DC Output Sink/Source Current, per Pin DC Supply Current, V _{CC} and GND Pins Power Dissipation in Still Air, Plastic DIP+ SOIC Package+ Storage Temperature Lead Temperature, 1 mm from Case for 10 Seconds	ParameterValueDC Supply Voltage (Referenced to GND)-0.5 to +7.0DC Input Voltage (Referenced to GND)-0.5 to V _{CC} +0.5DC Output Voltage (Referenced to GND)-0.5 to V _{CC} +0.5DC Input Current, per Pin±20DC Output Sink/Source Current, per Pin±50DC Supply Current, V _{CC} and GND Pins±50Power Dissipation in Still Air, Plastic DIP+ SOIC Package+500Storage Temperature-65 to +150Lead Temperature, 1 mm from Case for 10 Seconds260

^{*}Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

SOIC Package: : - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
				Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Referenced to		V_{CC}	V
	GND)			
TJ	Junction Temperature (PDIP)		140	°C
T _A	Operating Temperature, All Package Types		+85	°C
I _{ОН}	Output Current - High		-24	mA
I _{OL}	Output Current - Low		24	mA
t _r , t _f	Input Rise and Fall Time $*$ V _{CC} =4.5 V	0	10	ns/V
	(except Schmitt Inputs) V _{CC} =5.5 V	0	8.0	

 $V_{\rm IN}$ from 0.8 V to 2.0 V

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range GND \leq (V_{IN} or V_{OUT}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.



		ERISTICS (Voltages Refere	V _{CC}	,	Guaranteed			
				Limits				
Symbol	Parameter	Test Conditions	V	25 °C	-40°C to 85°C	Unit		
V _{IH}	Minimum High- Level Input Voltage	V_{OUT} =0.1 V or V_{CC} -0.1 V	4.5 5.5	2.0 2.0	2.0 2.0	V		
V _{IL}	Maximum Low - Level Input Voltage	V_{OUT} =0.1 V or V_{CC} -0.1 V	4.5 5.5	0.8 0.8	0.8 0.8	V		
V _{OH}	Minimum High- Level Output Voltage	I _{OUT} ≤ -50 μA	4.5 5.5	4.4 5.4	4.4 5.4	V		
		$\label{eq:VIN} \begin{array}{llllllllllllllllllllllllllllllllllll$	4.5 5.5	3.86 4.86	3.76 4.76			
V _{OL}	Maximum Low- Level Output Voltage	Ι _{ΟυΤ} ≤ 50 μΑ	4.5 5.5	0.1 0.1	0.1 0.1	V		
		$V_{IN}=V_{IH}$ or V_{IL} I _{OL} =24 mA I _{OL} =24 mA	4.5 5.5	0.36 0.36	0.44 0.44			
I _{IN}	Maximum Input Leakage Current	$V_{IN}=V_{CC}$ or GND	5.5	±0.1	±1.0	μA		
ΔI_{CCT}	Additional Max I _{cc} /Input	V _{IN} =V _{CC} - 2.1 V	5.5		1.5	mA		
I _{OLD}	+Minimum Dynamic Output Current	V _{OLD} =1.65 V Max	5.5		75	mA		
I _{OHD}	+Minimum Dynamic Output Current	V _{OHD} =3.85 V Min	5.5		-75	mA		
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{IN} =V _{CC} or GND	5.5	4.0	40	μA		

DC ELECTRICAL CHARACTERISTICS(Voltages Referenced to GND)

All outputs loaded; thresholds on input associated with output under test. +Maximum test duration 2.0 ms, one output loaded at a time.

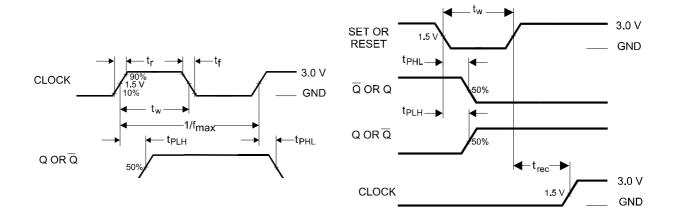
			Guaranteed Limits		mits	
Symbol	Parameter	25 °C		-40°C to		Unit
					85°C	
		Min	Max	Min	Max	
f _{max}	Maximum Clock Frequency (Figure 1)	145		125		MHz
t _{PLH}	Propagation Delay , Clock to Q or Q (Figure 1)	4.0	11.0	3.5	13.0	ns
t _{PHL}	Propagation Delay , Clock to Q or Q (Figure 1)	3.0	10.0	2.5	11.0	ns
t _{PLH}	Propagation Delay,Set or Reset to Q or Q (Figure 2)	2.5	9.5	2.0	10.5	ns
t _{PHL}	Propagation Delay , Set or Reset to Q or Q (Figure 2)	2.5	10.0	2.0	11.5	ns
CIN	Maximum Input Capacitance	4.5		4.5		pF

		Typical @25°C,V _{CC} =5.0 V	
C _{PD}	Power Dissipation Capacitance	35	рF

TIMING REQUIREMENTS(V_{CC}=5.0 V \pm 10%, C_L=50pF, Input t_r=t_f=3.0 ns)

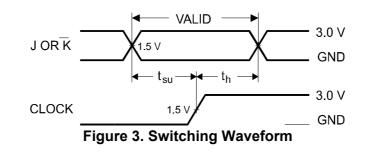
		Guarante		
Symbol	Parameter	25 °C	-40°C to	Unit
			85°C	
t _{su}	Minimum Setup Time, J or K to Clock	2.0	2.5	ns
	(Figure 3)			
t _h	Minimum Hold Time, Clock to J or K (Figure	2.0	2.0	ns
	3)			
t _w	Minimum Pulse Width, Set, Reset, Clock	5.0	6.0	ns
	(Figures 1,2)			
t _{rec}	Minimum Recovery Time, Set or Reset to	0	0	ns
	Clock (Figure 2)			











EXPANDED LOGIC DIAGRAM

